

196273US-0 CONT

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

Ende SHAN, et al.

SERIAL NO.: New Rule 1.53(b)
Continuation Application

:

: GROUP ART UNIT: 2823

: EXAMINER: EATON

FILED: Herewith

:

FOR: LOW TEMPERATURE
METALLIZATION PROCESS

:

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

In advance of prosecution, please amend the above-identified application as follows:

IN THE SPECIFICATION

page 4, line 22, replace "deposited. E.g.", with --deposited; e.g.--.

IN THE CLAIMS

Please amend the claims as follows:

1. (Amended) A method of forming a layer of metal on a substrate, comprising:
 - i) depositing a seed layer of the metal on a first substrate surface, said seed layer being sufficient to cover said first substrate surface;